





Type number	Package	Package description	Total product weight
PUMH11	SOT363	SC-88	5.47293 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator	
		MSL	PPT	MPPT	MSL	PPT	MPPT				
934049930135	3	1	260	30 s	1	235	20 s	3	D-22529 HAMBURG, Germany; Dongguan, China; Seremban, Malaysia		
934049930115	16	1	260	30 s	1	235	20 s	3	D-22529 HAMBURG, Germany; Dongguan, China; Seremban, Malaysia		

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.10000	100.00000	1.82717
		subTotal		0.10000	100.00000	1.82717
Lead Frame	Iron-nickel alloy	Aluminium (Al)	7429-90-5	0.00186	0.09000	0.03404
		Carbon (C)	7440-44-0	0.00083	0.04000	0.01513
		Chromium (Cr)	7440-47-3	0.00435	0.21000	0.07943
		Cobalt (Co)	7440-48-4	0.00890	0.43000	0.16264
		Iron (Fe)	7439-89-6	0.98118	47.40000	17.92787
		Manganese (Mn)	7439-96-5	0.01760	0.85000	0.32149
		Nickel (Ni)	7440-02-0	0.73920	35.71000	13.50642
		Phosphorus (P)	7723-14-0	0.00041	0.02000	0.00756
		Silicon (Si)	7440-21-3	0.00538	0.26000	0.09834
		Sulphur (S)	7704-34-9	0.00041	0.02000	0.00756
	Pure metal layer	Copper (Cu)	7440-50-8	0.27138	13.11000	4.95853
		Silver (Ag)	7440-22-4	0.03850	1.86000	0.70350
		subTotal		2.07000	100.00000	37.82251
Mould Compound	Filler	Silica fused	60676-86-0	2.19292	75.10000	40.06848
	Pigment	Carbon black	1333-86-4	0.00876	0.30000	0.16006
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.51100	17.50000	9.33686
		Phenol Formaldehyde resin (generic)	9003-35-4	0.20732	7.10000	3.78810
		subTotal		2.92000	100.00000	53.35350
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00001	0.00300	0.00020
		Bismuth (Bi)	7440-69-9	0.00000	0.00100	0.00007
		Copper (Cu)	7440-50-8	0.00000	0.00100	0.00007
		Lead (Pb)	7439-92-1	0.00002	0.00500	0.00034
	Tin solder	Tin (Sn)	7440-31-5	0.36996	99.99000	6.75987
		subTotal		0.37000	100.00000	6.76055
	Pure metal	Copper (Cu)	7440-50-8	0.01293	100.00000	0.23618
Wire		subTotal		0.01293	100.00000	0.23618

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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